

2ED020I12FA

Dual IGBT Driver IC
SP001054678



1 Overview

Main Features

- Dual channel isolated IGBT Driver
- For 600V/1200V IGBTs
- 2 A rail-to-rail output
- Vcesat-detection
- Active Miller Clamp



Product Highlights

- Coreless transformer isolated driver
- Basic insulation according to DIN EN 60747-5-2
- Basic insulation recognized under UL 1577
- Integrated protection features
- Suitable for operation at high ambient temperature
- AEC Qualified

Typical Application

- Drive inverters for HEV and EV
- Auxiliary inverters for HEV and EV
- High Power DC/DC inverters

Description

The 2ED020I12FA is a galvanic isolated dual channel IGBT driver in PG-DSO-36 package (32 pins) that provides two fully independent driver outputs with a current capability of typically 2A.

All logic pins are 5V CMOS compatible and could be directly connected to a microcontroller.

The data transfer across galvanic isolation is realized by the integrated Coreless Transformer Technology.

The 2ED020I12FA provides several protection features like IGBT desaturation protection, active Miller clamping and active shut down.

| Type | Package | Marking |
|-------------|-----------|-------------|
| 2ED020I12FA | PG-DSO-36 | 2ED020I12FA |

Table of Contents

| | | |
|----------|--|-----------|
| 1 | Overview | 1 |
| | Table of Contents | 2 |
| | List of Figures | 3 |
| | List of Tables | 4 |
| 2 | Block Diagram | 5 |
| 3 | Pin Configuration and Functionality | 6 |
| 3.1 | Pin Configuration | 6 |
| 3.2 | Pin Functionality | 7 |
| 4 | Functional Description | 9 |
| 4.1 | Introduction | 9 |
| 4.2 | Supply | 9 |
| 4.3 | Internal Protection Features | 11 |
| 4.3.1 | Undervoltage Lockout (UVLO) | 11 |
| 4.3.2 | READY Status Output | 11 |
| 4.3.3 | Watchdog Timer | 12 |
| 4.3.4 | Active Shut-Down | 12 |
| 4.4 | Non-Inverting and Inverting Inputs | 12 |
| 4.5 | Driver Outputs | 12 |
| 4.6 | External Protection Features | 12 |
| 4.6.1 | Desaturation Protection | 12 |
| 4.6.2 | Active Miller Clamp | 12 |
| 4.6.3 | Short Circuit Clamping | 12 |
| 4.7 | RESET | 12 |
| 5 | Electrical Parameters | 14 |
| 5.1 | Absolute Maximum Ratings | 14 |
| 5.2 | Operating Parameters | 16 |
| 5.3 | Recommended Operating Parameters | 16 |
| 5.4 | Electrical Characteristics | 17 |
| 5.4.1 | Voltage Supply | 17 |
| 5.4.2 | Logic Input and Output | 18 |
| 5.4.3 | Gate Driver | 19 |
| 5.4.4 | Active Miller Clamp | 19 |
| 5.4.5 | Short Circuit Clamping | 20 |
| 5.4.6 | Dynamic Characteristics | 20 |
| 5.4.7 | Desaturation Protection | 22 |
| 5.4.8 | Active Shut Down | 22 |
| 6 | Insulation Characteristics | 23 |
| 6.1 | Certified according to DIN EN 60747-5-2 (VDE 0884 Teil 2): 2003-01. Basic Insulation | 23 |
| 6.2 | Recognized under UL 1577 | 23 |
| 6.3 | Reliability | 23 |
| 7 | Timing Diagrams | 24 |
| 8 | Package Outlines | 26 |

List of Figures

| | | |
|----------|--|----|
| Figure 1 | Block Diagram 2ED020I12FA. | 5 |
| Figure 2 | PG-DSO-36 (top view) | 7 |
| Figure 3 | Application Example Bipolar Supply | 10 |
| Figure 4 | Application Example Unipolar Supply | 11 |
| Figure 5 | Propagation Delay, Rise and Fall Time | 24 |
| Figure 6 | Typical Switching Behavior. | 24 |
| Figure 7 | DESAT Switch-Off Behavior. | 25 |
| Figure 8 | UVLO Behavior. | 25 |
| Figure 9 | PG-DSO-36 (Plastic (Green) Dual Small Outline Package) | 26 |

List of Tables

| | | |
|----------|--|----|
| Table 1 | Pin Configuration | 6 |
| Table 2 | Absolute Maximum Ratings | 14 |
| Table 3 | Operating Parameters | 16 |
| Table 4 | Recommended Operating Parameters | 16 |
| Table 5 | Voltage Supply | 17 |
| Table 6 | Logic Input and Output | 18 |
| Table 7 | Gate Driver | 19 |
| Table 8 | Active Miller Clamp | 19 |
| Table 9 | Short Circuit Clamping | 20 |
| Table 10 | Dynamic Characteristics | 20 |
| Table 11 | Desaturation Protection | 22 |
| Table 12 | Active Shut Down | 22 |
| Table 13 | According to DIN EN 60747-5-2 | 23 |
| Table 14 | Recognized under UL 1577 | 23 |

Block Diagram

2 Block Diagram

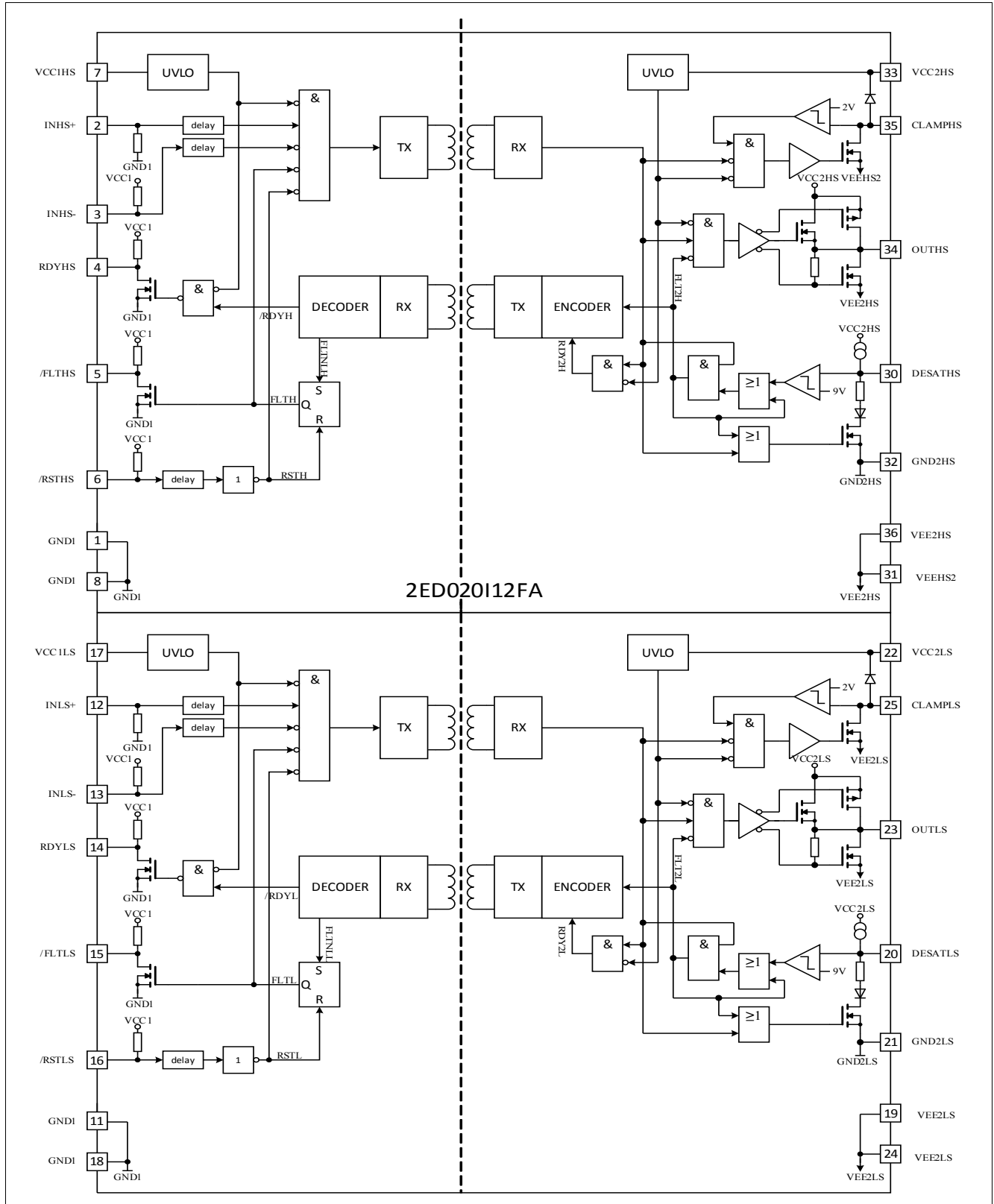


Figure 1 Block Diagram 2ED020I12FA

3 Pin Configuration and Functionality

3.1 Pin Configuration

Table 1 Pin Configuration

| Pin No. | Name | Function |
|---------|---------|--|
| 1 | GND1 | Common ground input side |
| 2 | INHS+ | Non inverted driver input high side |
| 3 | INHS- | Inverted driver input high side |
| 4 | RDYHS | Ready output high side |
| 5 | /FLTHS | Inverted fault output high side |
| 6 | /RSTHS | Inverted reset input high side |
| 7 | VCC1HS | Positive power supply input high side |
| 8 | GND1 | Common ground input side |
| 9 | NC | Not used, internally connected to Pin 10 |
| 10 | NC | Not used, internally connected to Pin 9 |
| 11 | GND1 | Common ground input side |
| 12 | INLS+ | Non inverted driver input low side |
| 13 | INLS- | Inverted driver input low side |
| 14 | RDYLS | Ready output low side |
| 15 | /FLTLS | Inverted fault output low side |
| 16 | /RSTLS | Inverted reset input low side |
| 17 | VCC1LS | Positive power supply input low side |
| 18 | GND1 | Common ground input side |
| 19 | VEE2LS | Negative power supply low side driver |
| 20 | DESATLS | Desaturation protection low side driver |
| 21 | GND2LS | Signal ground low side driver |
| 22 | VCC2LS | Power supply low side driver |
| 23 | OUTLS | Output low side driver |
| 24 | VEE2LS | Negative power supply low side driver |
| 25 | CLAMPLS | Miller clamping low side driver |
| 26 | | Pin not existing, cut out |
| 27 | | Pin not existing, cut out |
| 28 | | Pin not existing, cut out |
| 29 | | Pin not existing, cut out |
| 30 | DESATHS | Desaturation protection high side driver |
| 31 | VEE2HS | Negative power supply high side driver |

Pin Configuration and Functionality

Table 1 Pin Configuration (cont'd)

| Pin No. | Name | Function |
|---------|---------|--|
| 32 | GND2HS | Signal ground high side driver |
| 33 | VCC2HS | Power supply high side driver |
| 34 | OUTHS | Output high side driver |
| 35 | CLAMPHS | Miller clamping high side driver |
| 36 | VEE2HS | Negative power supply high side driver |

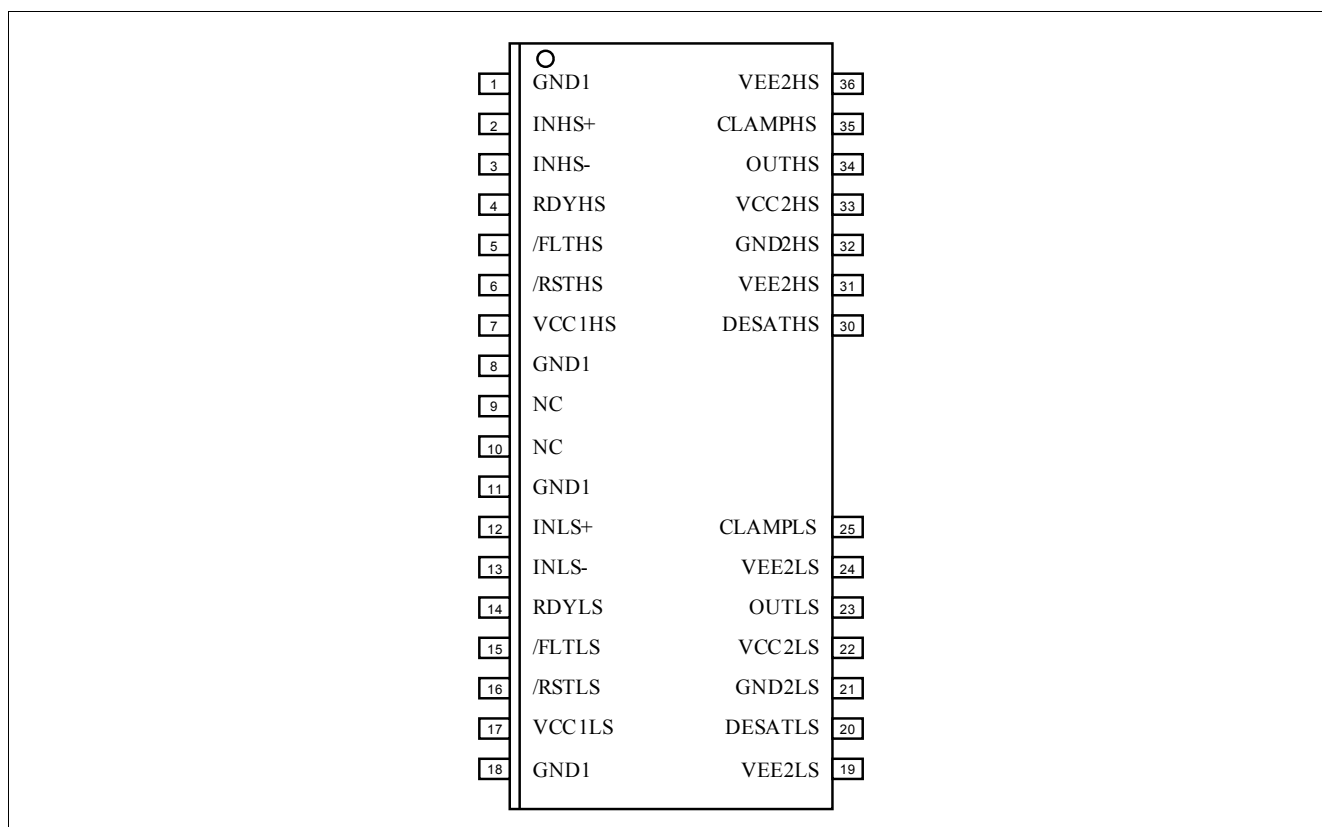


Figure 2 PG-DSO-36 (top view)

3.2 Pin Functionality

Remark: xxxHS and xxxLS at the end of pin name only indicates an order for description, both drivers are isolated and could be used as high side or low side without any preference.

GND1

Common ground connection of the input side.

INHS+, INLS+ Non Inverting Driver Input

Positive control signal for the driver output (see [Figure 6](#)).

A minimum pulse width is defined to make the IC robust against glitches at IN+. An internal pull-down-resistor ensures IGBT off-state.

Pin Configuration and Functionality

INHS-, INLS- Inverting Driver Input

Negative control signal for the driver output (see [Figure 6](#)).

A minimum pulse width is defined to make the IC robust against glitches at INxx-. An internal pull-up-resistor ensures IGBT off-state.

/RSTHS, /RSTLS Reset Input

Function 1: Enable/shutdown of the input chip (The IGBT is off if /RSTxx = low). A minimum pulse width is defined to make the IC robust against glitches at /RSTxx.

Function 2: Resets the DESAT-FAULT-state of the chip if /RSTxx is low for a time T_{RST} . An internal pull-up-resistor is used to ensure /FLTxx status output.

/FLTHS, /FLTLS Fault Output

Open-drain output to report a desaturation error of the IGBT (/FLTxx is low if desaturation occurs).

RDYHS, RDYLS Ready Status Output

Open-drain output to report the correct operation of the device (RDYxx = high if both chips are above the UVLO level and the internal chip transmission is faultless).

VCC1HS, VCC1LS Positive Supply

5 V power supply of the input chip

VEE2HS, VEE2LS Negative Supply

Negative power supply pins of the output chip. If no negative supply voltage is available, each pins has to be connected to its respective GND2xx.

DESATHS, DESATLS Desaturation Detection Input

Monitoring of the IGBT saturation voltage (V_{CE}) to detect desaturation caused by short circuits. If OUT is high, V_{CE} is above a defined value and a certain blanking time has expired, the desaturation protection is activated and the IGBT is switched off. The blanking time is adjustable by an external capacitor.

CLAMPHS, CLAMPLS Miller Clamping

Ties the gate voltage to ground after the IGBT has been switched off at a defined voltage to avoid a parasitic switch-on of the IGBT. During turn-off, the gate voltage is monitored and the clamp output is activated when the gate voltage goes below V_{CLAMP_TH} .

GND2HS, GND2LS Reference Ground

Reference ground of the output chip.

OUTHS, OUTLS Driver Output

Output pin to drive an IGBT. The voltage is switched between VEE2xx and VCC2xx. In normal operating mode Vout is controlled by INxx+, INxx- and /RSTxx. During error mode (UVLO, internal error or DESATxx Vout is driven to VEE2xx independent of the input control signals.

VCC2HS, VCC2LS Positive Supply

Positive power supply pin of the output side.

4 Functional Description

4.1 Introduction

The 2ED020I12FA is an advanced IGBT dual gate driver that can be also used for driving power MOS devices. Control and protection functions are included to make possible the design of high reliability systems.

The device consists of two galvanic separated driver. The input can be directly connected to a standard 5 V DSP or microcontroller with CMOS in/output and the output driver are connected to the high side and low side switch.

The rail-to-rail driver outputs enables the user to provide easy clamping of the IGBTs gate voltage during short circuit of the IGBT. So an increase of short circuit current due to the feedback via the Miller capacitance can be avoided. Further, a rail-to-rail output reduces power dissipation.

The device also includes IGBT desaturation protection with FAULT status outputs.

Two READY status outputs reports if the device is supplied and operates correctly.

4.2 Supply

The driver 2ED020I12FA is designed to support two different supply configurations, bipolar supply and unipolar supply.

In bipolar supply the driver is typically supplied with a positive voltage of 15V at VCC2 and a negative voltage of -8V at VEE2, please refer to [Figure 3](#). Negative supply prevents a dynamic turn on due to the additional charge which is generated from IGBT input capacitance times negative supply voltage. If an appropriate negative supply voltage is used, connecting CLAMPxx to IGBT gate is redundant and therefore typically not necessary.

Functional Description

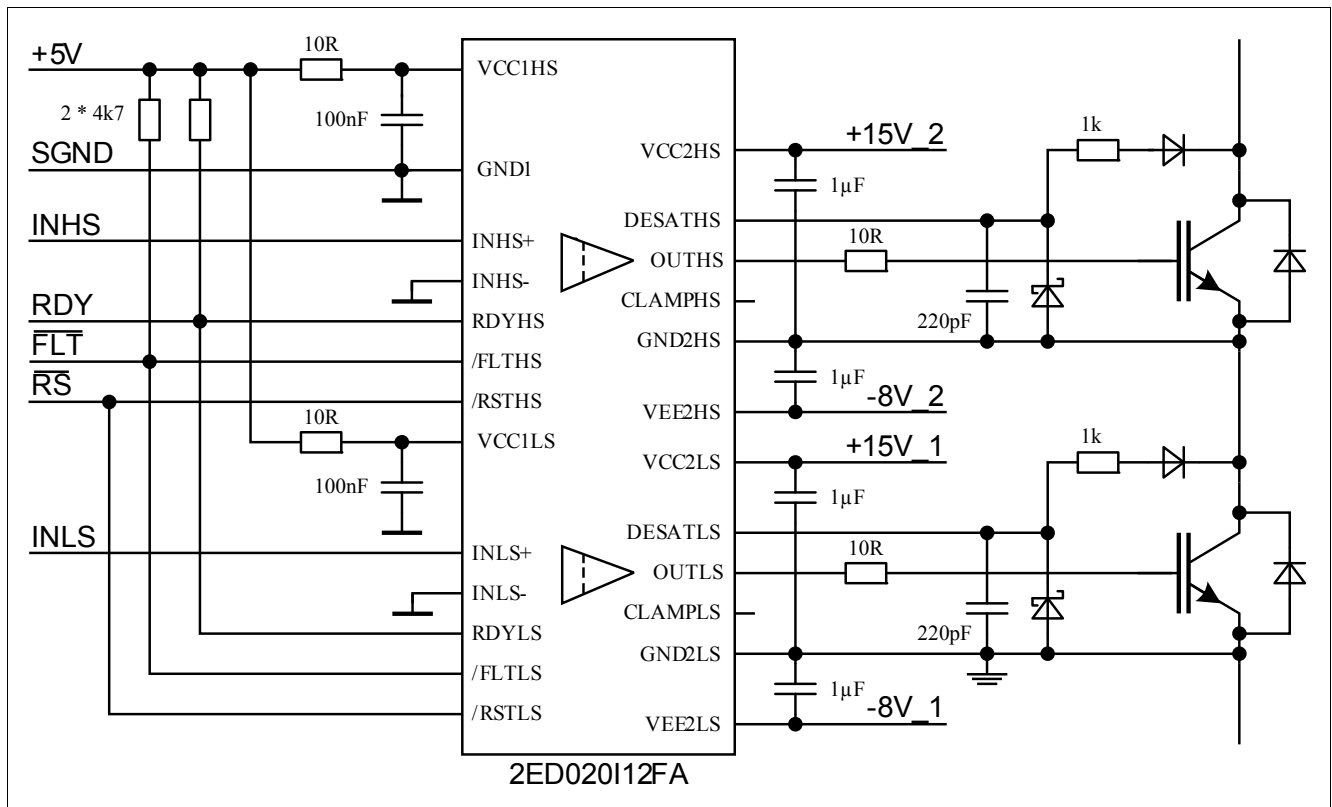


Figure 3 Application Example Bipolar Supply

For unipolar supply configuration the driver is typically supplied with a positive voltage of 15V at VCC2. Erratically dynamic turn on of the IGBT could be prevented with active Miller clamp function, so CLAMP output is directly connected to IGBT gate, please refer to [Figure 4](#).

Functional Description

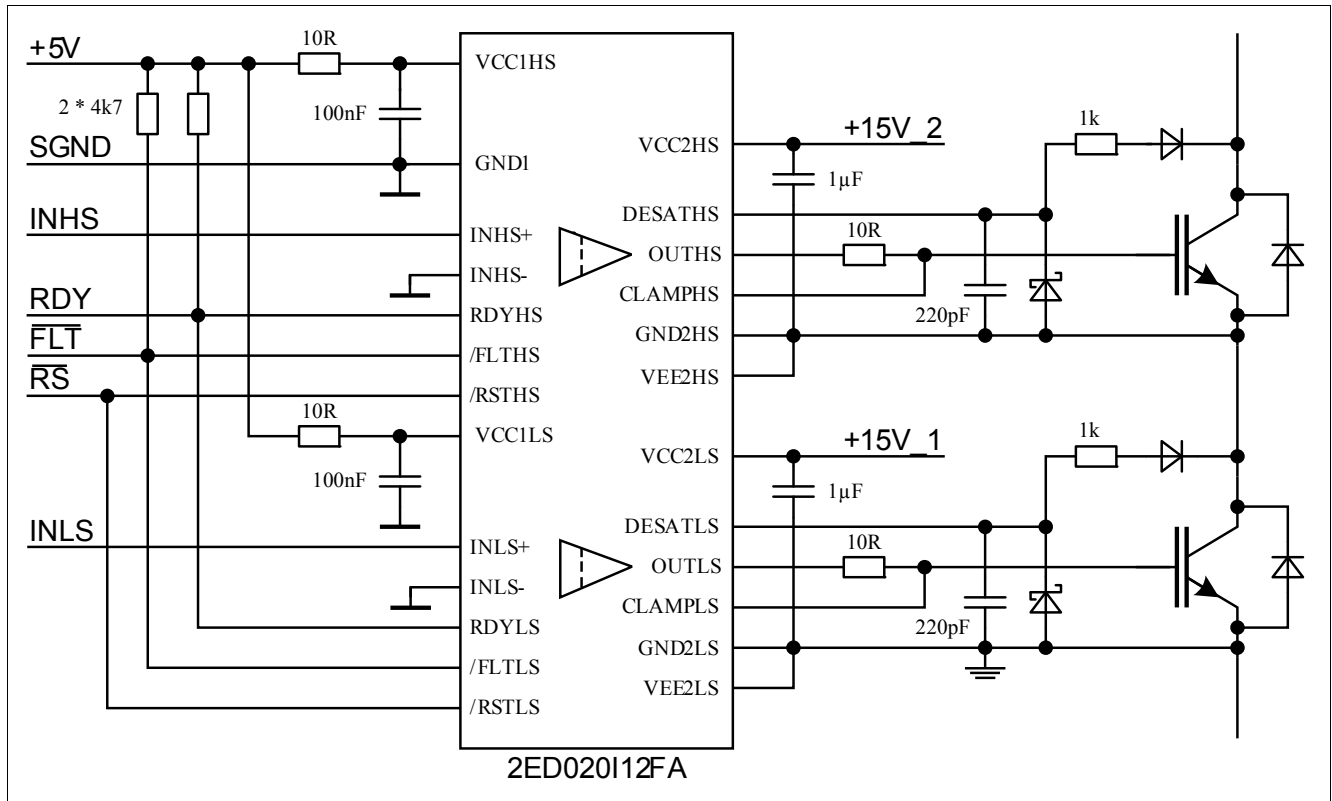


Figure 4 Application Example Unipolar Supply

4.3 Internal Protection Features

4.3.1 Undervoltage Lockout (UVLO)

To ensure correct switching of IGBTs the device is equipped with undervoltage lockout for all driver outputs as well as for input section, please see [Figure 8](#).

If the power supply voltage V_{VCC1xx} of the input section drops below V_{UVLO1} a turn-off signal is sent to the output driver before power-down. The IGBT is switched off and the signals at $INxx+$ and $INxx-$ are ignored as long as V_{VCC1xx} reaches the power-up voltage V_{UVLOH1} .

If the power supply voltage V_{VCC2xx} of the output driver goes down below V_{UVLO2} the IGBT is switched off and signals from the input chip are ignored as long as V_{VCC2xx} reaches the power-up voltage V_{UVLOH2} . $VEE2xx$ is not monitored.

4.3.2 READY Status Output

The READY outputs shows the status of three internal protection features.

- UVLO of the input chip
- UVLO of the output chip after a short delay
- Internal signal transmission after a short delay

It is not necessary to reset the READY signal since its state only depends on the status of the former mentioned protection signals.

Functional Description

4.3.3 Watchdog Timer

During normal operation the internal signal transmission is monitored by a watchdog timer. If the transmission fails for a given time, the IGBT is switched off and the READY output reports an internal error.

4.3.4 Active Shut-Down

The Active Shut-Down feature ensures a safe IGBT off-state if the output chip is not connected to the power supply, IGBT gate is clamped at OUTxx to VEE2xx.

4.4 Non-Inverting and Inverting Inputs

There are two possible input modes to control the IGBT. At non-inverting mode INxx+ controls the driver output while INxx- is set to low. At inverting mode INxx- controls the driver output while INxx+ is set to high, please see [Figure 6](#). A minimum input pulse width is defined to filter occasional glitches.

4.5 Driver Outputs

The output driver sections uses only MOSFETs to provide a rail-to-rail output. This feature permits that tight control of gate voltage during on-state and short circuit can be maintained as long as the drivers supply is stable. Due to the low internal voltage drop, switching behavior of the IGBT is predominantly governed by the gate resistor. Furthermore, it reduces the power to be dissipated by the driver.

4.6 External Protection Features

4.6.1 Desaturation Protection

A desaturation protection ensures the protection of the IGBT at short circuit. When the DESAT voltage goes up and reaches V_{DESAT_TH} , the output is driven low. Further, the FAULT output is activated, please refer to [Figure 7](#). A configurable blanking time is used to allow enough time for IGBT saturation. Blanking time is provided by a highly precise internal current source and an external capacitor.

4.6.2 Active Miller Clamp

In a half bridge configuration the switched off IGBT tends to dynamically turn on during turn on phase of the opposite IGBT. A Miller clamp allows sinking the Miller current across a low impedance path in this high dV/dt situation. Therefore in many applications, the use of a negative supply voltage can be avoided.

During turn-off, the gate voltage is monitored and the clamp output is activated when the gate voltage goes below V_{CLAMP_TH} . The clamp is designed for a Miller current up to I_{CLAMPL} .

4.6.3 Short Circuit Clamping

During short circuit the IGBTs gate voltage tends to rise because of the feedback via the Miller capacitance. An additional protection circuit connected to OUTxx and CLAMPxx limits this voltage to a value slightly higher than the supply voltage. A current of maximum 500 mA for 10 μ s may be fed back to the supply through one of this paths. If higher currents are expected or a tighter clamping is desired external Schottky diodes may be added.

4.7 RESET

The reset inputs have two functions.

Functional Description

Firstly, /RSTxx is in charge of setting back the FAULT output. If /RSTxx is low longer than a given time, /FLTxx will be cleared at the rising edge of /RSTxx; otherwise, it will remain unchanged. Moreover, it works as enable/shutdown of the input logic.

Electrical Parameters

5 Electrical Parameters

5.1 Absolute Maximum Ratings

Note: Absolute maximum ratings are defined as ratings, which when being exceeded may lead to destruction of the integrated circuit. Unless otherwise noted all parameters refer to GND1. The specification for all driver signals is valid for HS and LS with out special notice, e.g. IN+ covers INHS+ as well as INLS+. The signals from driver output side are measured with respect to their specific GND2HS or GND2LS.

Table 2 Absolute Maximum Ratings¹⁾

| Parameter | Symbol | Values | | Unit | Note |
|---|---------------|----------------|-----------------------------|---------|--|
| | | Min. | Max. | | |
| Positive power supply output side | V_{VCC2} | -0.3 | 20 | V | Referenced to GND2 |
| Negative power supply output side | V_{VEE2} | -12 | 0.3 | V | Referenced to GND2 |
| Maximum power supply voltage output side ($V_{VCC2} - V_{VEE2}$) | V_{max2} | - | 28 | V | - |
| Gate driver output | V_{OUT} | $V_{VEE2}-0.3$ | $V_{VCC2}+0.3$ | V | - |
| | | | $V_{VCC2}+$ V_{CLPout} | V | time < t_{CLPmax} , $I_{OUT} < 500$ mA (see Table 9) |
| Gate driver high output maximum current | I_{OUT} | - | 2.4 | A | t = 2 μ s |
| Gate & Clamp driver low output maximum current | I_{OUT} | - | 2.4 | A | t = 2 μ s |
| Maximum short circuit clamping time | t_{CLP} | - | 10 | μ s | $I_{CLAMP/OUT} = 500$ mA |
| Positive power supply input side | V_{VCC1} | -0.3 | 6.5 | V | - |
| Logic input voltages (IN+, IN-, RST) | $V_{LogicIN}$ | -0.3 | $V_{CC1} + 0.3$ | V | - |
| | | | 6.5 | V | - |
| Opendrain Logic output voltage (FLT) | $V_{FLT\#}$ | -0.3 | 6.5V | V | - |
| Opendrain Logic output voltage (RDY) | V_{RDY} | -0.3 | 6.5V | V | - |
| Opendrain Logic output current (FLT) | $I_{FLT\#}$ | - | 10 | mA | - |
| Opendrain Logic output current (RDY) | I_{RDY} | - | 10 | mA | - |
| Pin DESAT voltage | V_{DESAT} | -0.3 | $V_{VCC2} + 0.3$ | V | Referenced to GND2 |

Electrical Parameters

Table 2 Absolute Maximum Ratings (cont'd)¹⁾

| Parameter | Symbol | Values | | Unit | Note |
|------------------------------------|----------------|----------------|-------------------------------|------|---|
| | | Min. | Max. | | |
| Pin CLAMP voltage | V_{CLAMP} | $V_{VEE2}-0.3$ | $V_{VCC2}+0.3$ | V | – |
| | | $V_{VEE2}-0.3$ | $V_{VCC2}+$ $V_{CLPclamp}$ | V | time < t_{CLPmax} , $I_{CLAMP} < 500$ mA (see Table 9) |
| Junction temperature | T_J | -40 | 150 | °C | – |
| Storage temperature | T_S | -55 | 150 | °C | – |
| Power dissipation, per input part | $P_{D,IN}$ | – | 100 | mW | ²⁾ @ $T_A = 25^\circ\text{C}$ |
| Power dissipation, per output part | $P_{D,OUT}$ | – | 400 | mW | ²⁾ @ $T_A = 25^\circ\text{C}$ |
| Power dissipation, total | $P_{D,tot}$ | – | 1000 | mW | ²⁾ @ $T_A = 25^\circ\text{C}$ |
| Thermal resistance (Input part) | $R_{THJA,IN}$ | – | 375 | K/W | ²⁾ @ $T_A = 25^\circ\text{C}$, $P_{D,IN_HS+LS} = 200$ mW, $P_{D,OUT_HS+LS} =$ 800 mW |
| Thermal resistance (Output part) | $R_{THJA,OUT}$ | – | 110 | K/W | ²⁾ @ $T_A = 25^\circ\text{C}$, $P_{D,IN_HS+LS} = 200$ mW, $P_{D,OUT_HS+LS} =$ 800 mW |
| ESD Capability | V_{ESD} | – | 1 | kV | Human Body Model ³⁾ |

- 1) Not subject to production test. Absolute maximum Ratings are verified by design / characterization
- 2) IC power dissipation is derated linearly at 12 mW/°C above 65°C. Thermal performance may change significantly with layout and heat dissipation of components in close proximity.
- 3) According to EIA/JESD22-A114-B (discharging a 100 pF capacitor through a 1.5 kΩ series resistor).

Electrical Parameters

5.2 Operating Parameters

Note: Within the operating range the IC operates as described in the functional description. Unless otherwise noted all parameters refer to GND1. The specification for all driver signals is valid for HS and LS with out special notice, e.g. IN+ covers INHS+ as well as INLS+. The signals from driver output side are measured with respect to their specific GND2HS or GND2LS.

Table 3 Operating Parameters

| Parameter | Symbol | Values | | Unit | Note |
|---|-----------------|------------|------------|-------------|------------------------|
| | | Min. | Max. | | |
| Positive power supply output side | V_{VCC2} | 13 | 20 | V | referenced to GND2 |
| Negative power supply output side | V_{VEE2} | -12 | 0 | V | referenced to GND2 |
| Maximum power supply voltage output side ($V_{VCC2} - V_{VEE2}$) | V_{max2} | - | 28 | V | - |
| Positive power supply input side | V_{VCC1} | 4.5 | 5.5 | V | - |
| Pin CLAMP voltage | V_{CLAMP} | V_{VEE2} | V_{VCC2} | V | referenced to GND2 |
| Pin DESAT voltage | V_{DESAT} | 0 | V_{VCC2} | V | referenced to GND2 |
| Ambient temperature | T_A | -40 | 125 | °C | - |
| Common mode transient immunity | $ dV_{ISO}/dt $ | - | 50 | kV/ μ s | @ 500 V, ¹⁾ |

1) The parameter is not subject to production test - verified by design/characterization

5.3 Recommended Operating Parameters

Note: Unless otherwise noted all parameters refer to GND1. The specification for all driver signals is valid for HS and LS with out special notice, e.g. IN+ covers INHS+ as well as INLS+. The signals from driver output side are measured with respect to their specific GND2HS or GND2LS.

Table 4 Recommended Operating Parameters

| Parameter | Symbol | Value | Unit | Note / Test Condition |
|-----------------------------------|------------|-------|------|-----------------------|
| Positive power supply output side | V_{VCC2} | 15 | V | referenced to GND2 |
| Negative power supply output side | V_{VEE2} | -8 | V | referenced to GND2 |
| Positive power supply input side | V_{VCC1} | 5 | V | referenced to GND1 |

Electrical Parameters

5.4 Electrical Characteristics

Note: The electrical characteristics involve the spread of values for the supply voltages, load and junction temperatures given below. Typical values represent the median values, which are related to production processes at $T = 25^{\circ}\text{C}$. Unless otherwise noted all voltages are given with respect to GND. The specification for all driver signals is valid for HS and LS with out special notice, e.g. IN+ covers INHS+ as well as INLS+. The signals from driver output side are measured with respect to their specific GND2HS or GND2LS.

5.4.1 Voltage Supply

Table 5 Voltage Supply

| Parameter | Symbol | Values | | | Unit | Note |
|---|--------------|--------|------|------|------|---|
| | | Min. | Typ. | Max. | | |
| UVLO Threshold Input Chip | V_{UVLOH1} | – | 4.1 | 4.3 | V | – |
| | V_{UVLOL1} | 3.5 | 3.8 | – | V | – |
| UVLO Hysteresis Input Chip ($V_{UVLOH1} - V_{UVLOL1}$) | V_{HYS1} | 0.15 | – | – | V | – |
| UVLO Threshold Output Chip | V_{UVLOH2} | – | 12.0 | 12.6 | V | – |
| | V_{UVLOL2} | 10.4 | 11.0 | – | V | – |
| UVLO Hysteresis Output Chip ($V_{UVLOH1} - V_{UVLOL1}$) | V_{HYS2} | 0.7 | 0.9 | – | V | – |
| Quiescent Current Input Chip | I_{Q1} | – | 7 | 9 | mA | $V_{VCC1} = 5\text{ V}$ IN+ = High, IN- = Low =>OUT = High, RDY = High, /FLT = High |
| Quiescent Current Output Chip | I_{Q2} | – | 4 | 6 | mA | $V_{VCC2} = 15\text{ V}$ $V_{VEE2} = -8\text{ V}$ IN+ = High, IN- = Low =>OUT = High, RDY = High, /FLT = High |

Electrical Parameters

5.4.2 Logic Input and Output

Table 6 Logic Input and Output

| Parameter | Symbol | Values | | | Unit | Note |
|--|---|--------|------|-------------------|---------------|--|
| | | Min. | Typ. | Max. | | |
| IN+,IN-, $\overline{\text{RST}}$ Low Input Voltage | $V_{\text{IN+L}}$, $V_{\text{IN-L}}$, $V_{\text{RSTL\#}}$ | 0 | – | 1.5 | V | – |
| IN+,IN-, $\overline{\text{RST}}$ High Input Voltage | $V_{\text{IN+H}}$, $V_{\text{IN-H}}$, $V_{\text{RSTH\#}}$ | 3.5 | – | V_{VCC1} | V | – |
| IN-, $\overline{\text{RST}}$ Input Current | $I_{\text{IN-}}$, $I_{\text{RST\#}}$ | – | 100 | 400 | μA | $V_{\text{IN-}} = \text{GND1}$ $V_{\text{RST\#}} = \text{GND1}$ |
| IN+ Input Current | $I_{\text{IN+}}$ | – | 100 | 400 | μA | $V_{\text{IN+}} = \text{VCC1}$ |
| RDY, $\overline{\text{FLT}}$ Pull Up Current | I_{PRDY} , $I_{\text{PFLT\#}}$ | – | 100 | 400 | μA | $V_{\text{RDY}} = \text{GND1}$ $V_{\text{FLT\#}} = \text{GND1}$ |
| Input Pulse Suppression IN+, IN- | $T_{\text{MININ+}}$, $T_{\text{MININ-}}$ | 30 | 40 | – | ns | |
| Input Pulse Suppression $\overline{\text{RST}}$ for ENABLE/SHUTDOWN | T_{MINRST} | 30 | 40 | – | ns | – |
| Pulse Width $\overline{\text{RST}}$ for Resetting $\overline{\text{FLT}}$ | T_{RST} | 800 | – | – | ns | – |
| FLT Low Voltage | V_{FLTL} | – | – | 300 | mV | $I_{\text{SINK(FLT\#)}} = 5 \text{ mA}$ |
| RDY Low Voltage | V_{RDYL} | – | – | 300 | mV | $I_{\text{SINK(RDY)}} = 5 \text{ mA}$ |

Electrical Parameters

5.4.3 Gate Driver

Table 7 Gate Driver

| Parameter | Symbol | Values | | | Unit | Note |
|--------------------------------|--------------------|------------------------|--------------------------|--------------------------|------|--|
| | | Min. | Typ. | Max. | | |
| High Level Output Voltage | V_{OUTH1} | $V_{\text{CC2}} - 1.2$ | $V_{\text{CC2}} - 0.8$ | – | V | $I_{\text{OUTH}} = -20 \text{ mA}$ |
| | V_{OUTH2} | $V_{\text{CC2}} - 2.5$ | $V_{\text{CC2}} - 2.0$ | – | V | $I_{\text{OUTH}} = -200 \text{ mA}$ |
| | V_{OUTH3} | $V_{\text{CC2}} - 9$ | $V_{\text{CC2}} - 5$ | – | V | $I_{\text{OUTH}} = -1 \text{ A}$ |
| | V_{OUTH4} | | $V_{\text{CC2}} - 10$ | – | V | $I_{\text{OUTH}} = -2 \text{ A}^{1)}$ |
| High Level Output Peak Current | I_{OUTH} | -1.5 | -2.0 | – | A | IN+ = High, IN- = Low; OUT = High |
| Low Level Output Voltage | V_{OUTL1} | – | $V_{\text{VEE2}} + 0.04$ | $V_{\text{VEE2}} + 0.09$ | V | $I_{\text{OUTL}} = 20 \text{ mA}$ |
| | V_{OUTL2} | – | $V_{\text{VEE2}} + 0.3$ | $V_{\text{VEE2}} + 0.85$ | V | $I_{\text{OUTL}} = 200 \text{ mA}$ |
| | V_{OUTL3} | – | $V_{\text{VEE2}} + 2.1$ | $V_{\text{VEE2}} + 5$ | V | $I_{\text{OUTL}} = 1 \text{ A}$ |
| | V_{OUTL4} | – | $V_{\text{VEE2}} + 7$ | – | V | $I_{\text{OUTL}} = 2 \text{ A}^{1)}$ |
| Low Level Output Peak Current | I_{OUTL} | 1.5 | 2.0 | – | A | IN+ = Low, IN- = Low; OUT = Low, $V_{\text{VCC2}} = 15 \text{ V}$, $V_{\text{VEE2}} = -8 \text{ V}$ |

1) Not subject to production test. Absolute maximum Ratings are verified by design / characterization

5.4.4 Active Miller Clamp

Table 8 Active Miller Clamp

| Parameter | Symbol | Values | | | Unit | Note |
|-------------------------|------------------------|--------|--------------------------|--------------------------|------|-------------------------------------|
| | | Min. | Typ. | Max. | | |
| Low Level Clamp Voltage | V_{CLAMPL1} | – | $V_{\text{VEE2}} + 0.03$ | $V_{\text{VEE2}} + 0.08$ | V | $I_{\text{CLAMP}} = 20 \text{ mA}$ |
| | V_{CLAMPL2} | – | $V_{\text{VEE2}} + 0.3$ | $V_{\text{VEE2}} + 0.8$ | V | $I_{\text{CLAMP}} = 200 \text{ mA}$ |
| | V_{CLAMPL3} | – | $V_{\text{VEE2}} + 1.9$ | $V_{\text{VEE2}} + 4.8$ | V | $I_{\text{CLAMP}} = 1 \text{ A}$ |
| Low Level Clamp Current | I_{CLAMPL} | 2 | – | – | A | ¹⁾ |
| Clamp Threshold Voltage | $V_{\text{CLAMP_TH}}$ | 1.6 | 2.1 | 2.4 | V | Related to VEE2 |

1) The parameter is not subject to production test - verified by design/characterization

Electrical Parameters

5.4.5 Short Circuit Clamping

Table 9 Short Circuit Clamping

| Parameter | Symbol | Values | | | Unit | Note |
|---|----------------|--------|------|------|------|--|
| | | Min. | Typ. | Max. | | |
| Clamping voltage (OUT) ($V_{OUT} - V_{VCC2}$) | V_{CLPout} | – | 0.8 | 1.3 | V | IN+ = High, IN- = Low, OUT = High $I_{OUT} = 500$ mA pulse test, $t_{CLPmax} = 10$ μ s) |
| Clamping voltage (CLAMP) ($V_{VCLAMP} - V_{VCC2}$) | $V_{CLPclamp}$ | – | 1.3 | – | V | IN+ = High, IN- = Low, OUT = High $I_{CLAMP} = 500$ mA (pulse test, $t_{CLPmax} = 10$ μ s) ¹⁾ |
| | | – | 0.7 | 1.1 | V | IN+ = High, IN- = Low, OUT = High $I_{CLAMP} = 20$ mA |

1) Not subject to production test. Absolute maximum Ratings are verified by design / characterization

5.4.6 Dynamic Characteristics

Table 10 Dynamic Characteristics¹⁾

| Parameter | Symbol | Values | | | Unit | Note |
|--|---------------|--------|------|------|------|---|
| | | Min. | Typ. | Max. | | |
| Input IN to output propa- gation delay ON | T_{PDON} | 145 | 170 | 195 | ns | $C_{LOAD} = 100$ pF $V_{IN+} = 50\%$, $V_{OUT} = 50\%$ @ 25°C |
| Input IN to output propa- gation delay OFF | T_{PDOFF} | 145 | 165 | 190 | ns | |
| Input IN to output propa- gation delay distortion ($T_{PDOFF} - T_{PDON}$) | T_{PDISTO} | -35 | -5 | 25 | ns | |
| Input IN to output propa- gation delay ON variation due to temp | T_{PDONt} | 160 | 190 | 220 | ns | $C_{LOAD} = 100$ pF $V_{IN+} = 50\%$, $V_{OUT} = 50\%$ @ 125°C |
| Input IN to output propa- gation delay OFF variation due to temp | T_{PDOFFt} | 165 | 195 | 225 | ns | |
| Input IN to output propa- gation delay distortion ($T_{PDOFF} - T_{PDON}$) | $T_{PDISTOt}$ | -25 | 5 | 35 | ns | |

Electrical Parameters

Table 10 Dynamic Characteristics¹⁾ (cont'd)

| Parameter | Symbol | Values | | | Unit | Note |
|--|---------------|--------|------|------|------|---|
| | | Min. | Typ. | Max. | | |
| Input IN to output propagation delay ON variation due to temp | T_{PDONt} | 135 | 165 | 195 | ns | $C_{LOAD} = 100 \text{ pF}$ $V_{IN+} = 50\%$, $V_{OUT} = 50\% @ -40^{\circ}\text{C}$ |
| Input IN to output propagation delay OFF variation due to temp | T_{PDOFFt} | 125 | 155 | 185 | ns | |
| Input IN to output propagation delay distortion ($T_{PDOFF} - T_{PDON}$) | $T_{PDISTOt}$ | -40 | -10 | 20 | ns | |
| Rise Time | T_{RISE} | 10 | 30 | 60 | ns | $C_{LOAD} = 1 \text{ nF}$ $V_L 10\%, V_H 90\%$ |
| | | 200 | 400 | 800 | ns | $C_{LOAD} = 34 \text{ nF}$ $V_L 10\%, V_H 90\%$ |
| Fall Time | T_{FALL} | 10 | 50 | 90 | ns | $C_{LOAD} = 1 \text{ nF}$ $V_L 10\%, V_H 90\%$ |
| | | 200 | 350 | 600 | ns | $C_{LOAD} = 34 \text{ nF}$ $V_L 10\%, V_H 90\%$ |

1) Measured under the following conditions: $V_{VCC1}=5\text{V}$, $V_{VEE2}=-8\text{V}$, $V_{VCC2}=15\text{V}$

Electrical Parameters

5.4.7 Desaturation Protection

Table 11 Desaturation Protection

| Parameter | Symbol | Values | | | Unit | Note |
|--------------------------------------|-------------------|--------|------|------|---------------|---|
| | | Min. | Typ. | Max. | | |
| Blanking Capacitor Charge Current | I_{DESATC} | 450 | 500 | 550 | μA | $V_{VCC2} = 15\text{ V}$, $V_{VEE2} = -8\text{ V}$ $V_{DESAT} = 2\text{ V}$ |
| Blanking Capacitor Discharge Current | I_{DESATD} | 9.0 | 14 | – | mA | $V_{VCC2} = 15\text{ V}$, $V_{VEE2} = -8\text{ V}$ $V_{DESAT} = 6\text{ V}$ |
| Desaturation Reference Level | V_{DESAT_TH} | 8.3 | 9 | 9.5 | V | $V_{VCC2} = 15\text{ V}$ |
| Desaturation Filter Time | $T_{DESATfilter}$ | – | 250 | – | ns | $V_{VCC2} = 15\text{ V}$, $V_{VEE2} = -8\text{ V}$ $V_{DESAT} = 9\text{ V}^{1)}$ |
| Desaturation Sense to OUT Low Delay | $T_{DESATOUT}$ | – | 350 | 430 | ns | $V_{OUT} = 90\%$ $C_{LOAD} = 1\text{ nF}$ |
| Desaturation Sense to FLT Low Delay | $T_{DESATFLT}$ | – | – | 2.25 | μs | $V_{FLT\#} = 10\%$; $I_{FLT\#} = 5\text{ mA}$ |
| Desaturation Low Voltage | V_{DESATL} | 0.4 | 0.6 | 0.95 | V | IN+ = Low, IN- = Low, OUT = Low |
| Leading edge blanking | $T_{DESATleb}$ | – | 400 | – | ns | ¹⁾ |

1) Not subject to production test. This parameter is verified by design / characterization

5.4.8 Active Shut Down

Table 12 Active Shut Down

| Parameter | Symbol | Values | | | Unit | Note |
|--------------------------|-------------|--------|------|------|------|---|
| | | Min. | Typ. | Max. | | |
| Active Shut Down Voltage | V_{ACTSD} | – | – | 2.0 | V | $I_{OUT} = -200\text{ mA}$, V_{CC2} open, referenced to VEE2 |

6 Insulation Characteristics

Insulation characteristics are guaranteed only within the safety maximum ratings which must be ensured by protective circuits in application. Surface mount classification is class A in accordance with CECC00802.

This coupler is suitable for “basic insulation” only within the safety ratings. Compliance with the safety ratings shall be ensured by means of suitable protective circuits.

6.1 Certified according to DIN EN 60747-5-2 (VDE 0884 Teil 2): 2003-01. Basic Insulation

Table 13 According to DIN EN 60747-5-2

| Description | Symbol | Characteristics | Unit |
|---|------------|-----------------------|------------|
| Installation classification per EN 60664-1, Table 1 for rated mains voltage $\leq 150 V_{RMS}$ for rated mains voltage $\leq 300 V_{RMS}$ for rated mains voltage $\leq 600 V_{RMS}$ | | I-IV I-III I-II | – |
| Climatic Classification | | 55/125/21 | – |
| Pollution Degree (EN 60664-1) | | 2 | – |
| Minimum External Clearance between input and driver section | CLR | 8.2 | mm |
| Minimum External Creepage between input and driver section | CPG | 8.2 | mm |
| Minimum External Clearance between HS- and LS-driver output | | 2.75 | mm |
| Minimum External Creepage between HS- and LS-driver output | | 2.85 | mm |
| Minimum Comparative Tracking Index | CTI | 175 | |
| Maximum Repetitive Insulation Voltage | V_{IORM} | 1420 | V_{PEAK} |
| Highest Allowable Overvoltage | V_{IOTM} | 6000 | V_{PEAK} |
| Maximum Surge Insulation Voltage | V_{IOSM} | 6000 | V |

6.2 Recognized under UL 1577

Table 14 Recognized under UL 1577

| Description | Symbol | Characteristics | Unit |
|--------------------------------------|-----------|-----------------|-----------|
| Insulation Withstand Voltage / 1 min | V_{ISO} | 3750 | V_{rms} |
| Insulation Test Voltage / 1 s | V_{ISO} | 4500 | V_{rms} |

6.3 Reliability

For Qualification Report please contact your local Infineon Technologies office.

7 Timing Diagrams

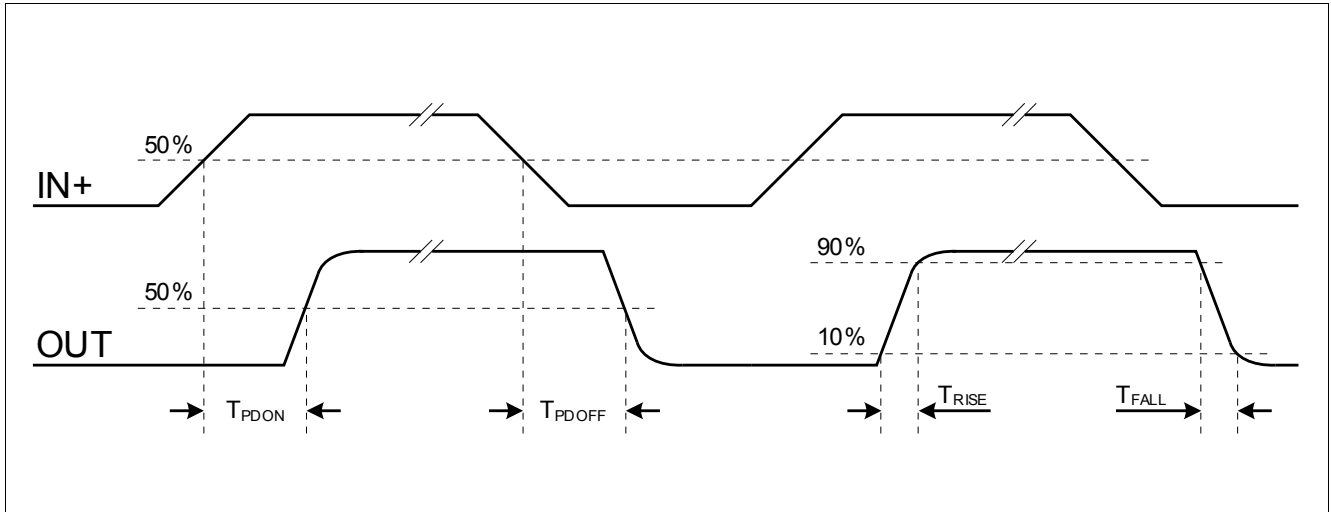


Figure 5 Propagation Delay, Rise and Fall Time

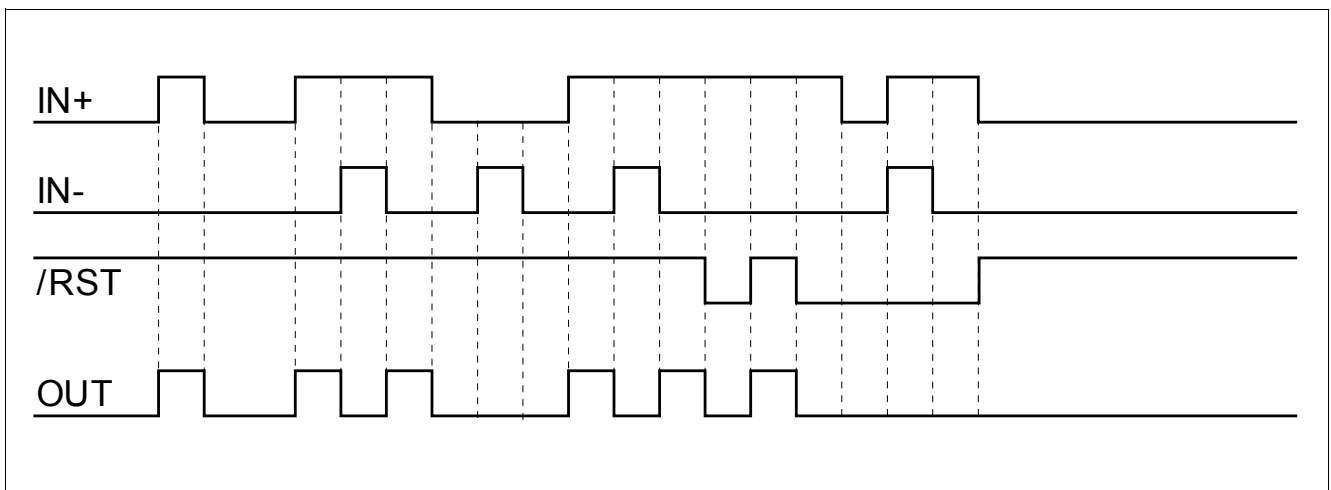


Figure 6 Typical Switching Behavior

Timing Diagrams

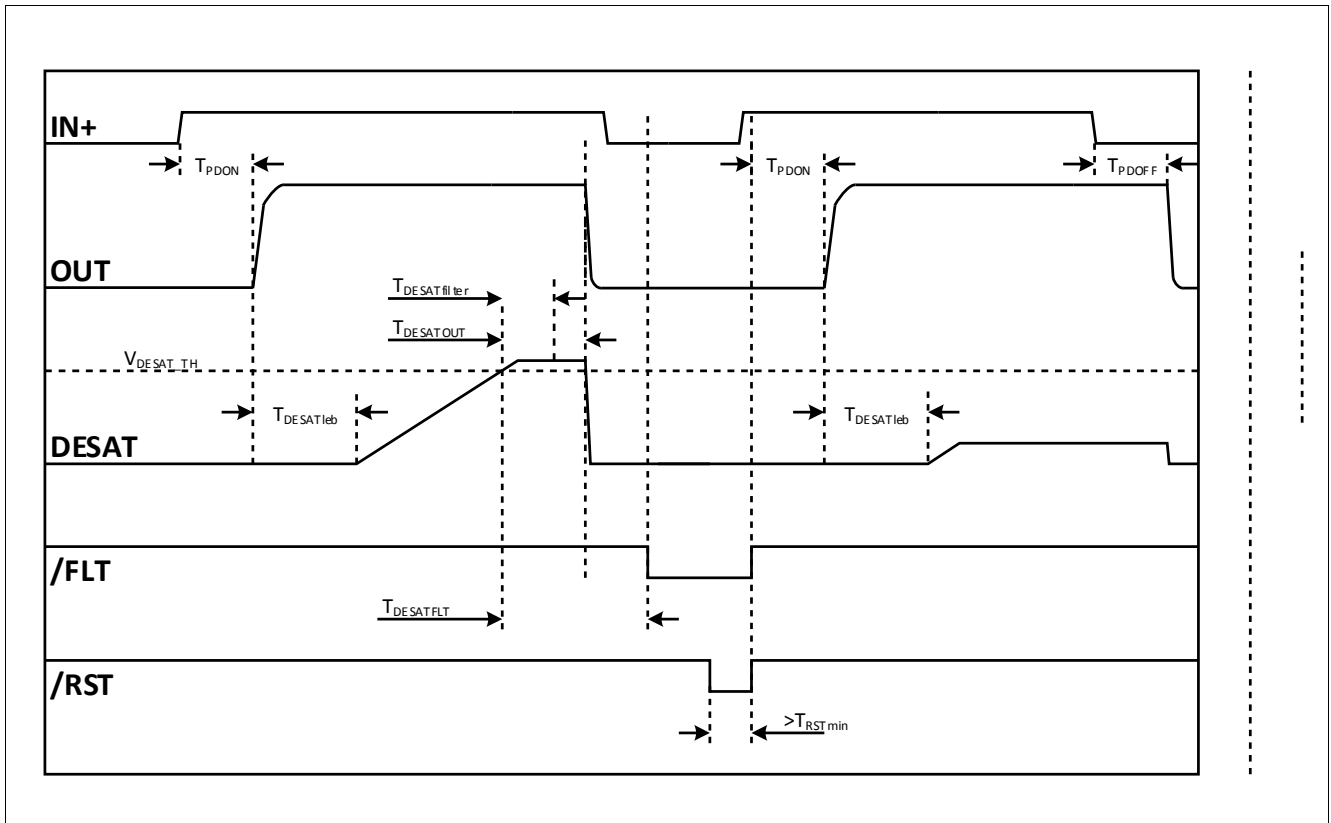


Figure 7 DESAT Switch-Off Behavior

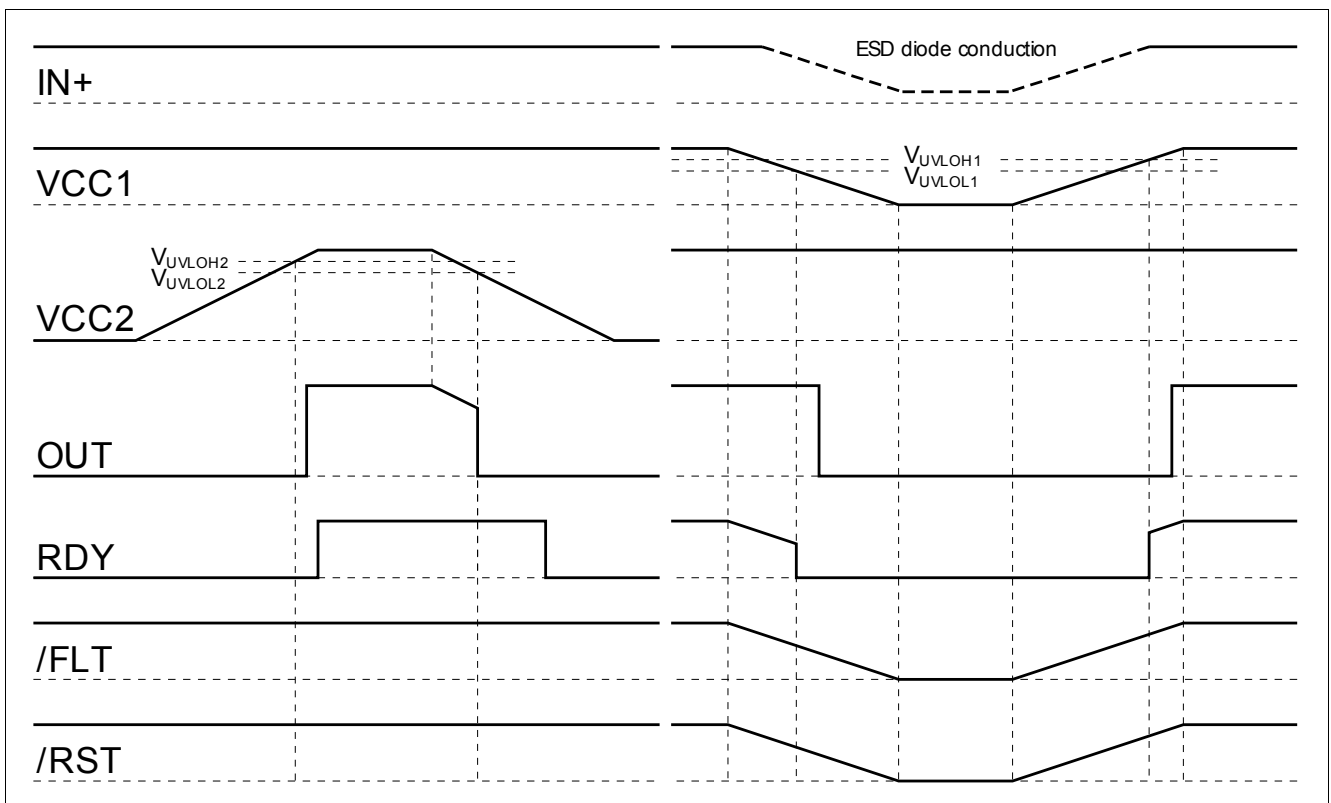


Figure 8 UVLO Behavior

8 Package Outlines

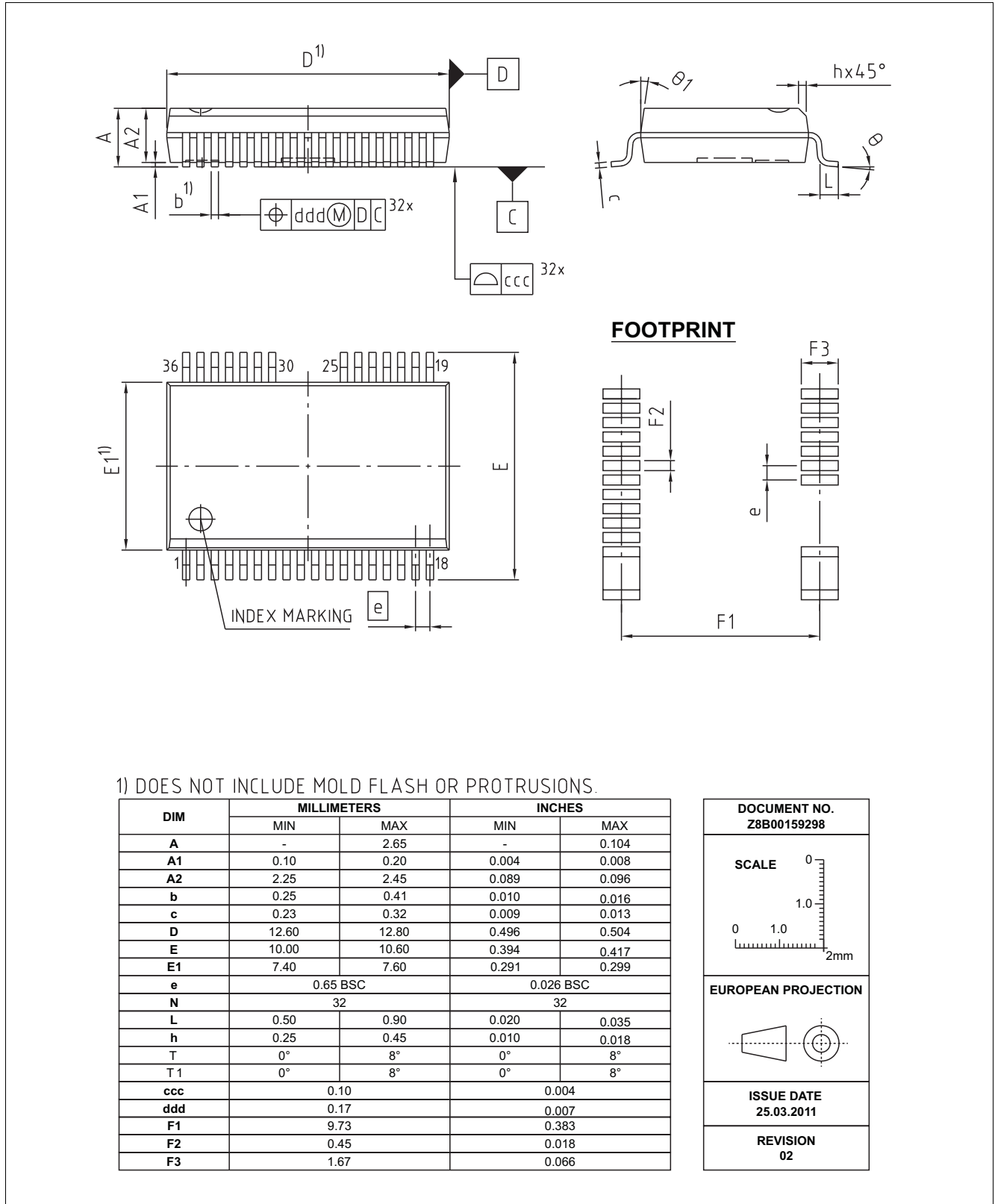


Figure 9 PG-DSO-36 (Plastic (Green) Dual Small Outline Package)

Revision History

| Page or Item | Subjects (major changes since previous revision) |
|----------------------------|---|
| Rev 3.1, 2016-04-05 | |
| Rev 3.0, 2015-11-27 | |
| All | Update latest template |
| Page 7 | Removed Figure 1 “Typical Application”. |
| Page 5 | Updated Figure 1 . |
| Page 7 | Updated INHS+ and INLS+ description. |
| Page 8 | Updated INHS- and INLS- description. |
| Page 14 | Updated Table 2 . |
| Page 16 | Updated Table 3 . |
| Page 18 | Updated Table 6 . |
| Page 19 | Updated Table 7 (added footnote). |
| Page 20 | Updated Table 9 (added footnote). |

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